

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC62HxxxxxPR-G
Typical Mass: 57 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.724	Silicon	12700	7440-21-3
Leadframe	24.392	Copper	427900	7440-50-8
	0.016	Tin	300	7440-31-5
	0.218	Silver	3800	7440-22-4
Die attach	0.126	Silver	2200	7440-22-4
	0.032	Epoxy	600	—
Bonding wire	0.040	Gold	700	7440-57-5
Resin	26.825	Silica	470600	60676-86-0
	2.189	Epoxy resin	38400	—
	1.580	Phenol resin	27700	—
	0.428	Metal hydroxide	7500	—
Plating	0.430	Tin	7500	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."